

Part Number: **BAT400D-p-F**

Weight (mg): 8.79

(HF Date Code Limited. See Data Sheet.)

Part Numbers:

2N7002DW-7-F	2N7002DW-13-F
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Element	Material Group	Materials	CAS (if applicable)	Average mass homogeneous Material(%)	Percent of whole (%)	Mass (mg)	ppm Homogeneous Material	ppm overall
Chip	Silicon w/Metal	Doped Silicon*	7440-21-3	100.00%	3.09	0.27	1000000	30855
Leadframe	Alloy 42	Fe	7439-89-6	57.65%	29.92	2.63	576500	172495
		Ni	7440-02-0	41.00%			410000	122676
		Mn	7439-96-5	0.60%			6000	1795
		Cr(not Cr 6+)	7440-47-3	0.10%			1000	299
		Co	7440-48-4	0.50%			5000	1496
		Si	7440-21-3	0.15%			1500	449
Leadframe Plating	Silver	Silver	7440-22-4	100.00%	1.18	0.10	1000000	11760
Bond Wire	Copper Wire	Cu	7440-50-8	100.00%	0.11	0.01	1000000	1137
Molding compound	KTMC-1050G	SiO2	60676-86-0	69.00%	61.56	5.41	690000	424737
		Epoxy Resin	29690-82-2	14.00%			140000	86178
		Phenol Resin	9003-35-4	7.00%			70000	43089
		Mg(OH)2	1309-42-8	8.00%			80000	49245
		C	1333-86-4	0.20%			2000	1231
		others	----	1.80%			18000	11080
Die attached epoxy	84-1 LMISR4	Ag	7440-22-4	75.00%	1.24	0.11	750000	9314
		epoxy resin	Trade secret	20.00%			200000	2484
		curing agent & hardener	Trade secret	5.00%			50000	621
Lead Plating Finish	Matte Tin	Tin	7440-31-5	100.00%	2.91	0.26	1000000	29058
					Total	100.00	8.79	1000000

Tolerance ±10%

This data is based on information provided by our suppliers. We believe it to be correct but do not routinely validate it by measurement. It is for guidance only and Diodes Inc. does not guarantee its absolute accuracy or completeness

* The Silicon Chip is doped at atomic levels with trace amounts of elements that may include Phosphorus, Boron, Arsenic, and other elements. Metalization may include Titanium, Nickel, Aluminum, Silver or Gold. These substances are not reported where their concentration is less than the minimum reportable level per the guidelines specified in the Tables of EIA JIG-101, [Material Composition Declaration for Electronic Products](#).

This product or product family does not contain any of the following substances except as **CURRENTLY** exempted by ELV II and RoHS and reported above:

Asbestos	Organic tin compounds
Antimony Compounds	Ozone Depleting Substances - Class I (CFCs, HBFCs, etc.)
Azo compounds	Ozone Depleting Substances - Class II (HCFCs)
Cadmium and cadmium compounds	Perfluorooctane Sulphonate (PFOS) or related compounds
Certain Shortchain Chlorinated Paraffins	Polybrominated biphenyls (PBB) and Polybrominated diphenyl ethers (PBDE) including DecaBDE
Chlorinated organic compounds	Polychlorinated Biphenyls (PCBs)
Halogens	Polychlorinated Naphthalenes (> 3 chlorine atoms)
Hexavalent chromium compounds	Radioactive Substances
Lead and lead compounds	Tributyl Tin (TBT) and Triphenyl Tin (TPT)
Mercury and mercury compounds	Tributyl Tin Oxide (TBTO)